

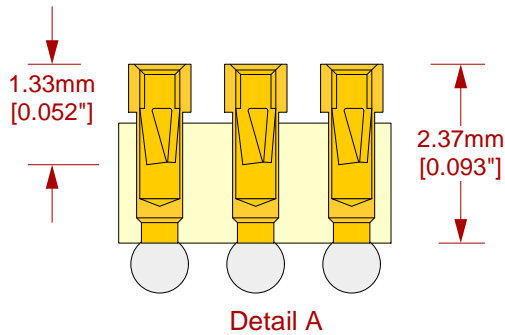
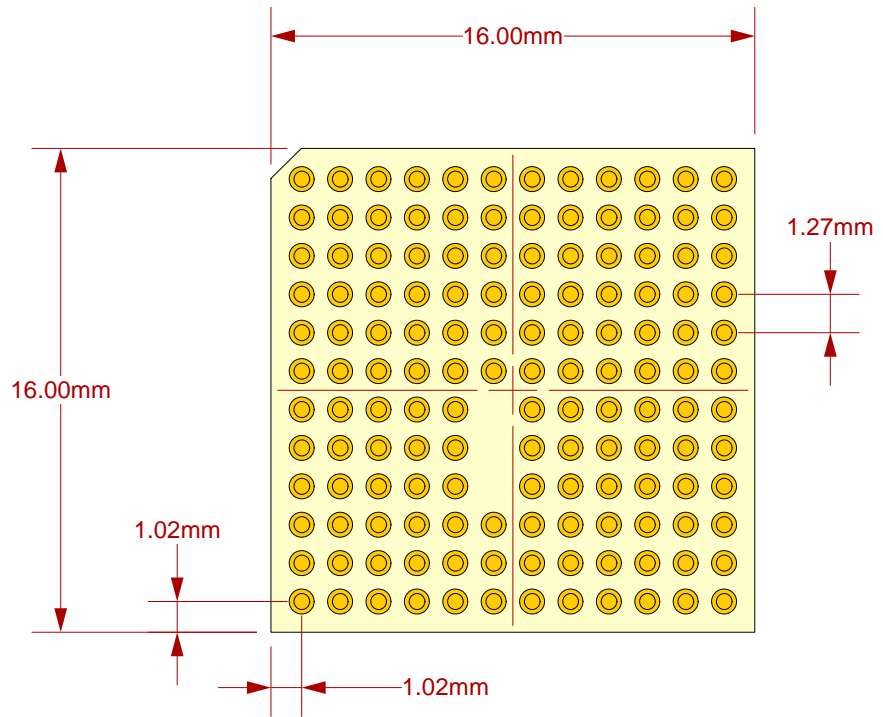
Patent Pending

Top View

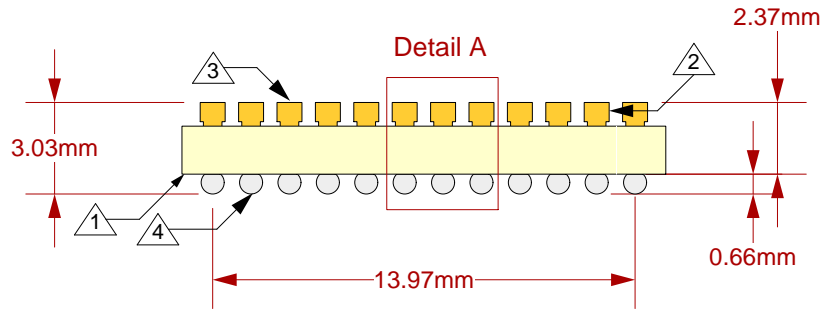
Ordering Information:

Solder Ball Alloy	Part Number Suffix
Sn63Pb37	-32
Sn96.5Ag3.0Cu0.5	-32F*

*RoHS Compliant



Side View



- ① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"]
FR4/G10 or equivalent high temp material. (RoHS)
- ② Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- ③ Contacts: Beryllium Copper Alloy172, HT; Finish-
0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- ④ Solder balls: (See Table above)


CONTACT DATA

Accepts 0.20mm - 0.33mm Diameter pins
3-finger
37/25 gram, Initial insertion force (with 0.254mm/0.203mm dia. pin)
30/22 gram, normal force (with 0.254mm/0.203mm dia. pin)
20/17 gram, extraction force (with 0.254mm/0.203mm dia. pin)

Description: Giga-snaP BGA SMT Foot

141 position (1.27mm pitch) gold plated female receptacle pins to SMT solder balls. Pin assignment 1:1.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.18mm [\pm 0.007"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA141A-B-32(F) Drawing		Status: Released	Scale: 4:1	Rev: A
 <p>© 2012 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	Drawing: S. Faiz		Date: 02/20/2013	
	File: SF-BGA141A-B-32 Dwg		Modified:	